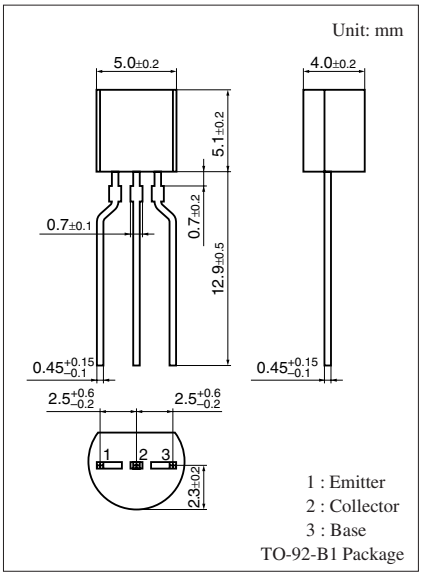
2SA1018

Silicon PNP epitaxial planar type

For general amplification
Complementary to 2SC1473



■ Features

- High collector-emitter voltage (Base open) V_{CEO}

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	−250	V
Collector-emitter voltage (Base open)	V_{CEO}	−200	V
Emitter-base voltage (Collector open)	V_{EBO}	−5	V
Collector current	I_C	−70	mA
Peak collector current	I_{CP}	−100	mA
Collector power dissipation	P_C	750	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

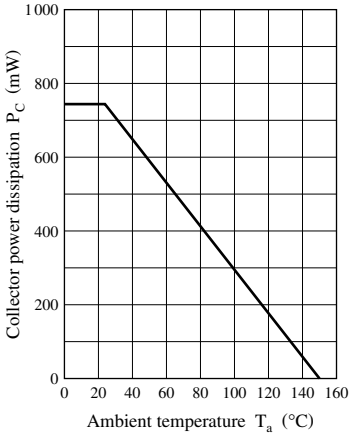
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -100$ µA, $I_B = 0$	−200			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -1$ µA, $I_C = 0$	−5			V
Collector-emitter cut-off current (Base open)	I_{CEO}	$V_{CE} = -120$ V, $I_B = 0$			−1	µA
Forward current transfer ratio *	h_{FE}	$V_{CE} = -10$ V, $I_C = -5$ mA	60		220	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -50$ mA, $I_B = -5$ mA			−1.5	V
Transition frequency	f_T	$V_{CB} = -10$ V, $I_E = 10$ mA, f = 200 MHz	50			MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10$ V, $I_E = 0$, f = 1 MHz			10	pF

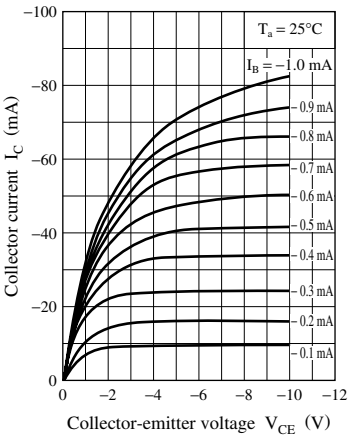
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Rank classification

Rank	Q	R
h_{FE}	60 to 150	100 to 220

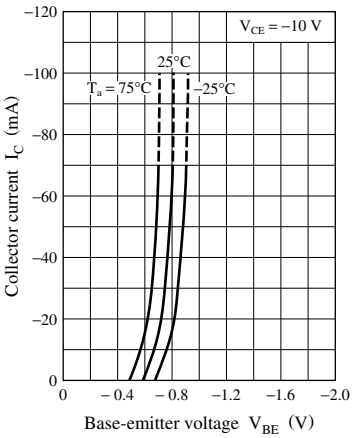
P_C — T_a



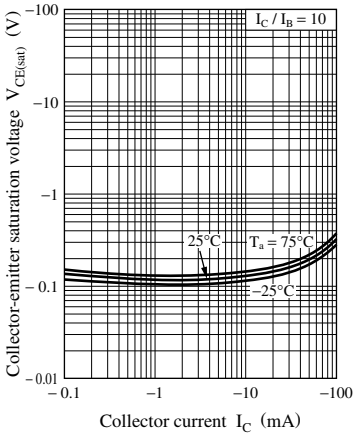
I_C — V_{CE}



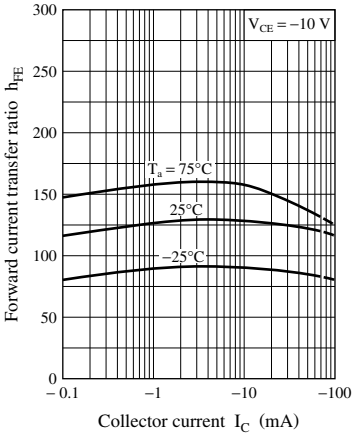
I_C — V_{BE}



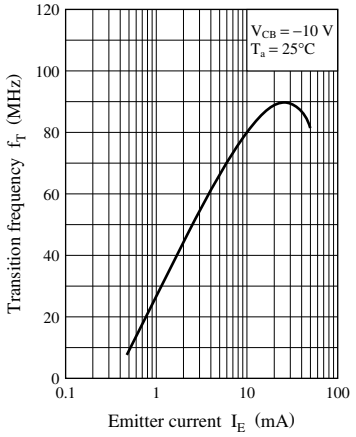
$V_{CE(sat)}$ — I_C



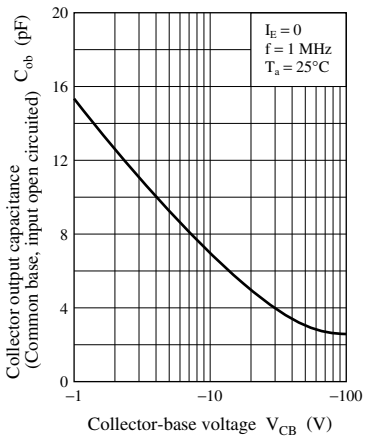
h_{FE} — I_C



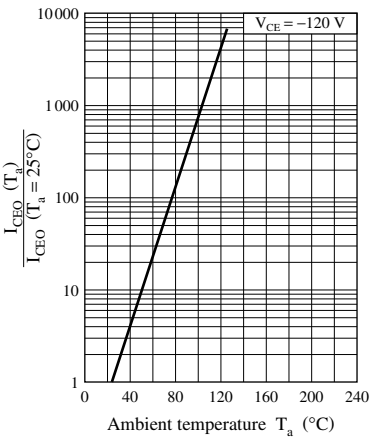
f_T — I_E



C_{ob} — V_{CB}



I_{CEO} — T_a



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